

Title (en)  
MULTI-CHIP PRINTHEAD ASSEMBLER

Title (de)  
MEHRCHIP-DRUCKKOPF-ASSEMBLER

Title (fr)  
DISPOSITIF D'ASSEMBLAGE DE TÊTE D'IMPRESSION MULTI-PUCE

Publication  
**EP 2321848 A4 20121107 (EN)**

Application  
**EP 08782947 A 20080819**

Priority  
AU 2008001199 W 20080819

Abstract (en)  
[origin: WO2010019985A1] The invention relates to an assembler for assembling printhead integrated circuitry on a carrier. The assembler includes a support assembly, a wafer positioning assembly arranged on the support assembly and configured to retain and position a wafer defining a plurality of die to be picked from the wafer; and a die picking assembly arranged on the support assembly and configured to pick a pre-selected dice from the wafer. The assembler also includes a die placement assembly arranged on the support assembly and configured to receive the preselected dice and to place the dice on the carrier, and a die conveyance mechanism arranged on the support assembly and configured to convey the dice from the die picking assembly to the die placement assembly. Further included is a control system operatively engaged with the wafer positioning, die picking, die placement and die conveyance assemblies to control operation thereof.

IPC 8 full level  
**H01L 21/67** (2006.01); **H05K 13/04** (2006.01)

CPC (source: EP KR)  
**H01L 21/50** (2013.01 - KR); **H01L 21/67132** (2013.01 - EP); **H01L 21/67144** (2013.01 - EP); **H01L 24/75** (2013.01 - EP); **H05K 13/021** (2013.01 - EP); **H05K 13/04** (2013.01 - KR); **H01L 2924/01006** (2013.01 - EP); **H01L 2924/01023** (2013.01 - EP); **H01L 2924/01033** (2013.01 - EP); **H01L 2924/01075** (2013.01 - EP); **H01L 2924/01082** (2013.01 - EP); **H01L 2924/14** (2013.01 - EP)

Citation (search report)

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- [X] US 6086641 A 20000711 - SHIRONOUCHI TOSHIAKI [JP]
- [X] KR 20070037824 A 20070409 - SAMSUNG ELECTRONICS CO LTD [KR]
- See references of WO 2010019985A1

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)  
**WO 2010019985 A1 20100225**; EP 2321848 A1 20110518; EP 2321848 A4 20121107; KR 101178010 B1 20120828; KR 20110036038 A 20110406

DOCDB simple family (application)  
**AU 2008001199 W 20080819**; EP 08782947 A 20080819; KR 20117000773 A 20080819